EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L10	38674	(embed$4 encapsula$5) near3 (component device module IC chip or micro adj circuit microcircuit) same (base sheet film layer insulat$3 dielectric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 17:52
L11	10355	10 and (pcb board motherboard) and (conduct$4 metal$3) same (base sheet film layer insulat$3 dielectric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 17:53
L13	5165	11 and (component device module IC chip or micro adj circuit microcircuit) same (opening recess$3 trench groove)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 17:54
L15	1508	13 and ((second additional other) with (component device module IC chip or micro adj circuit microcircuit)) same (opening recess$3 trench groove) same (base sheet film layer insulat$3 dielectric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 17:55
L16	859	15 and (@ad<"20030918" @rlad<"20030918")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 17:56
L17	604	16 and (base sheet film layer insulat$3 dielectric) same (polymer glass-fibre FR4 PI polyimide FR5 aramid polytetrafluoroethylene Teflon LCP "liquid crystal polymer" pre-hardened adj binder prepreg)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 18:03
L18	518	17 and ("438"/$.ccls. "257"/$.ccls. "216"/$.ccls. "174"/$.ccls. "29"/$.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 18:05

L19	392	18 and (component device module IC chip or micro adj circuit microcircuit) same (pattern$5) same (conduct$4 metal$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 18:09
L20	1	(US-20070206366-$).did.	US-PGPUB	OR	ON	2009/11/06 18:17
L21	1	(US-7513037-$).did.	USPAT	OR	ON	2009/11/06 18:29
L22	1	(US-6972964-$).did.	USPAT	OR	ON	2009/11/06 18:36
L23	3	20 21 22	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 18:47
L24	64	((component device module IC chip or micro adj circuit microcircuit) same (pattern$5) same (conduct$4 metal$3) same (glu$3 adhesive) same (base sheet film layer insulat$3 dielectric) same (opening recess $3 trench groove) same (second additional other)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 18:52
L25	3	(((second additional other) adj (component device module IC chip or micro adj circuit microcircuit)) same (pattern$5) same (conduct$4 metal$3) same (glu$3 adhesive) same (base sheet film layer insulat$3 dielectric) same (opening recess $3 trench groove)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 18:54

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L26	2	(((second additional other) adj (component device module IC chip or micro adj circuit microcircuit)) same (pattern$5) same (conduct$4 metal$3) same (glu$3 adhesive) same (base sheet film layer insulat$3 dielectric) same (opening recess$3 trench groove)).clm.	USPAT; UPAD	OR	ON	2009/11/06 18:59

11/6/2009 7:00:46 PM
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